mtiinstruments

325 Washington Avenue Ext., Albany, NY 12205

Wafer measurement report for customer reference and pre-sales Of Proforma 300iSA

Prepared by: Engineer Name

Date: 10/1/2020

Wafer measurements performed by: Engineer Name, and Senior Engineer

1 Customer information

- 1.1 Company name: Prospective Customer
- 1.2 Contact name: John Doe (jdoe@prospective.com)

2 Supplied materials

2.1 FOUP containing the following wafer:



3 Customer supplied instructions/documentation

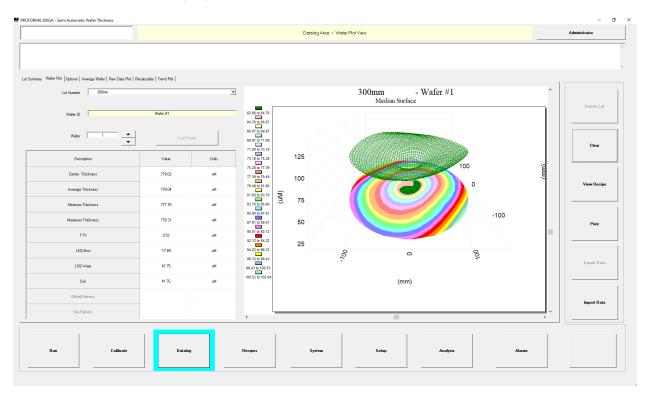
Wafer Type	Number of wafers to measure	Measurements requested
Flat	1	Standard measurement

4 Measurement data

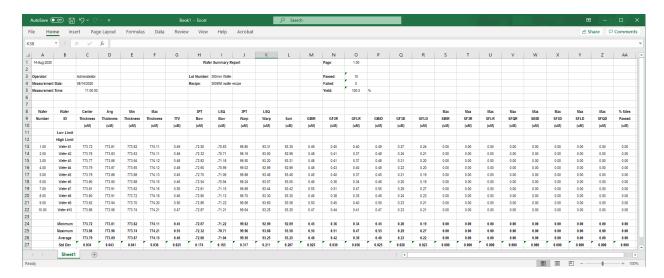
4.1 First wafer

Wafer Type	Number of wafers to measure	Measurements requested
Flat	1	Standard measurement

Wafer 123123123123 1 (Flat). ID side down.



The image above displays a wafer plot that can be rotated and flipped to allow for multiple angles of inspection. Measurements like thickness, total thickness variation, bow and warp are shown. The measurements to be taken or excluded can be specified in the wafer recipe file. The additional tabs allow for other methods to display and analyze the information. A CSV file with the raw data is also provided, see sample below.



5 Results summary

Wafer measurements were carried out as per request. For each measurement, the readings were taken 10 times, this provides more accuracy. Data will show a "Wafer #1" which represents the data for the first of the ten readings and not necessarily different wafers.

Wafer calibration was done using an MTI test wafer with SN: XXXX and center thickness of 728.79 um.

The recipe created for this trial had a 3mm exclusion zone and 8mm circumferential and radial spacing.

5.1 Conclusion

All measurements appear nominal. A comma separated variable file with the raw data has also been provided.